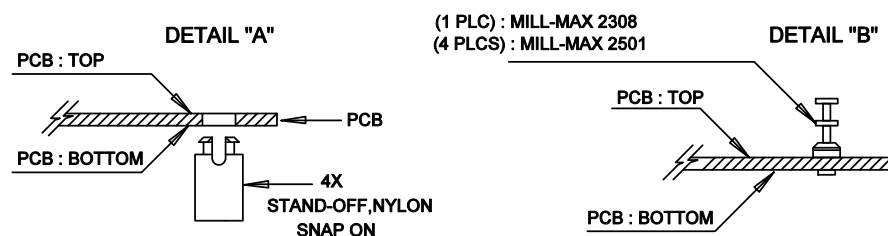
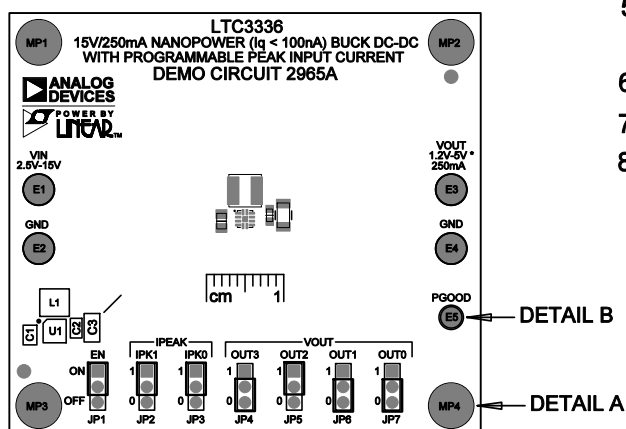


REVISION HISTORY				
ECO	REV	DESCRIPTION	APP. ENG.	DATE
-	01	PRODUCTION	ZP	10-22-20

NOTES: UNLESS OTHERWISE SPECIFIED

1. WORKMANSHIP SHALL BE IN ACCORDANCE WITH IPC-A-610.
2. ASSEMBLY REFLOW PROFILE SHALL BE IN ACCORDANCE WITH J-STD-020 WITH MAXIMUM SOLDER TEMPERATURE OF 250 DEGREES CELSIUS.
3. PARTS TO OMIT WILL BE SPECIFIED ON THE BILL OF MATERIALS
LOCATIONS OF OMITTED PARTS SHALL BE FREE OF SOLDER.
MASK THE SOLDER STENCIL WHERE SMT PARTS ARE OMITTED.
4. INSTALL SHUNTS AS SHOWN ON ASSY DRAWING.
5. DEPANELIZE BOARDS AFTER ASSEMBLY AND ROUTE-OUT THE BREAKOUT TABS ON FOUR SIDES OF THE BOARD EDGE.
6. APPLY ASSEMBLY STAMP OR QA STAMP TO BOTTOM OF BOARD (UNSHOWY AREA).
7. INSTALL TURRETS, STAND-OFFS AS SHOWN BELOW:
8. APPLY DEMO S/N AT AREA ON BOTTOM SIDE AS SHOWN ON SHEET 2.



(1 PLC) : MILL-MAX 2308
(4 PLCS) : MILL-MAX 2501

APPROVALS		ANALOG DEVICES POWER BY LINEAR™ FOR ADI CUSTOMER USE ONLY		
PCB DES	NC	TITLE: TOP ASSEMBLY DRAWING 15V/250mA NANOPOWER (Iq < 100nA) BUCK DC-DC WITH PROGRAMMABLE PEAK INPUT CURRENT		
APP ENG	ZP			
		SIZE	IC NO. LTC3336	REV.
		N/A	DEMO CIRCUIT 2965A	01
SCALE = NONE		SHT 1 OF 1		